

Tektronix Component Solutions Increases ASIC and FPGA Test Capacity Selects Teradyne J750 Semiconductor Test Systems

BEAVERTON, Ore. -- June 7, 2011 -- Tektronix Component Solutions announced today the investment in five new Teradyne J750EX semiconductor test systems to allow screening of a wider variety of complex ASICs, increase test capacity and enable faster development of new test programs. Reducing development time will improve time-to-test for customers and reduce development cost.

The addition of the popular Teradyne systems will significantly expand the company's test and screening services for high-density and high-speed ASICs and FPGAs for military, space, and commercial aerospace customers. Furthermore, the new systems can provide memory testing of digital devices up to 384-pins and test increasingly complex digital ICs. Typical application areas include full characterization of off-the-shelf parts at extended temperature ranges, verifying that device performance meets demanding military, aerospace or space standards.

"We're making a significant capital investment to better serve the needs of the high performance mil-aero market," said Tom Buzak, president, Tektronix Component Solutions. "We are fully committed to equipping our labs with state-of-the-art technology. The Teradyne test systems will help decrease test development time, reducing the cost of test for our customers while enabling the screening of increasingly complex devices." About Component Test and Screening Services A strong complement to Tektronix Component Solutions' design, assembly, and test capabilities for custom microelectronics, component screening refers to the testing of electronic components to verify their quality and performance complies with the manufacturer's specifications and meets the customer's application performance and reliability criteria. Examples of the component test services provided by Tektronix Component Solutions include:

Electrical - Surge testing, parametric testing, functional testing, and device characterization Package integrity - highly accelerated stress testing (HAST), particle impact noise detection (PIND), salt fog, thermal shock and temp-cycle, and plastic encapsulated microcircuit (PEM) testing Assembly evaluation - destructive physical analysis (DPA), prohibited materials analysis (PMA), scanning electron microscopy (SEM) and X-Ray Life-testing - Burn-in, operational life, dynamics, endurance and climatic test

Tektronix Component Solutions' services are tailored to test complex parts that will operate in the harsh conditions of military, space and commercial aerospace applications.

About Tektronix Component Solutions Tektronix Component Solutions is a proven microelectronics services provider offering a complete range of custom design, prototyping, manufacturing, and test services to equipment manufacturers. With more than 40 years of experience serving the measurement, military, medical, and communications markets, Tektronix Component Solutions works as an extension of our customers' product teams to cost-effectively resolve the most demanding component challenges. Headquartered in Beaverton, Oregon, Tektronix Component Solutions can be found on the web at component-solutions.tektronix.com.

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